

LCD EMI Filter Array with ESD Protection

CM1420, CM1422

Description

The CM1420 and CM1422 are EMI filter arrays with ESD protection, which integrate six and eight Pi-filters (C–R–C), respectively. The CM1420/22 has component values of 15 pF – 100 Ω – 15 pF. These devices include ESD protection diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of ± 15 kV, well beyond the maximum requirement of the IEC 61000–4–2 international standard. Using the MIL–STD–883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ± 30 kV.

This device is particularly well suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of its small package format and easy-to-use pin assignments. In particular, the CM1420/22 is ideal for EMI filtering and protecting data lines from ESD for the LCD display in clamshell handsets.

The CM1420 and CM1422 incorporate OptiGuard coating which results in improved reliability at assembly. The CM1420 and CM1422 are available in space-saving, low-profile chip scale packages with RoHS compliant lead-free finishing.

Features

- Functionally and Pin Compatible with CSPEMI606 (CM1420) and CSPEMI608 (CM1422) Devices
- OptiGuard Coated for Improved Reliability at Assembly
- Six and Eight Channels of EMI Filtering
- ± 15 kV ESD Protection on Each Channel (IEC 61000–4–2 Level 4, Contact Discharge)
- ± 30 kV ESD Protection on Each Channel (HBM)
- Better than 30 dB of Attenuation at 1 GHz to 3 GHz
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum Filter and ESD Performance
- 15–Bump, 2.960 mm x 1.330 mm Footprint Chip Scale Package (CM1420)
- 20–Bump, 4.000 mm x 1.458 mm Footprint Chip Scale Package (CM1422)
- These Devices are Pb–Free and are RoHS Compliant

Applications

- LCD Data Lines in Clamshell Wireless Handsets
- EMI Filtering & ESD Protection for High–Speed I/O Data Ports
- Wireless Handsets / Cell Phones
- Notebook Computers
- PDAs / Handheld PCs
- EMI Filtering for High–Speed Data Lines

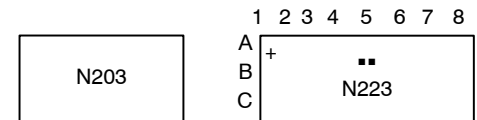


WLCSP15
CP SUFFIX
CASE 567BS



WLCSP20
CP SUFFIX
CASE 567BZ

MARKING DIAGRAM



CM1420 15–Bump CSP Package CM1422 20–Bump CSP Package

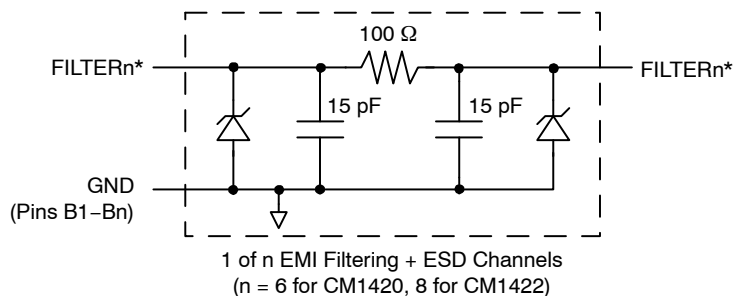
N203 = CM1420–03CP
N223 = CM1422–03CP

ORDERING INFORMATION

Device	Package	Shipping [†]
CM1420–03CP	CSP–15 (Pb–Free)	3500/Tape & Reel
CM1422–03CP	CSP–20 (Pb–Free)	3500/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

BLOCK DIAGRAM



*See Package/Pinout Diagrams for expanded pin information.

PACKAGE / PINOUT DIAGRAMS

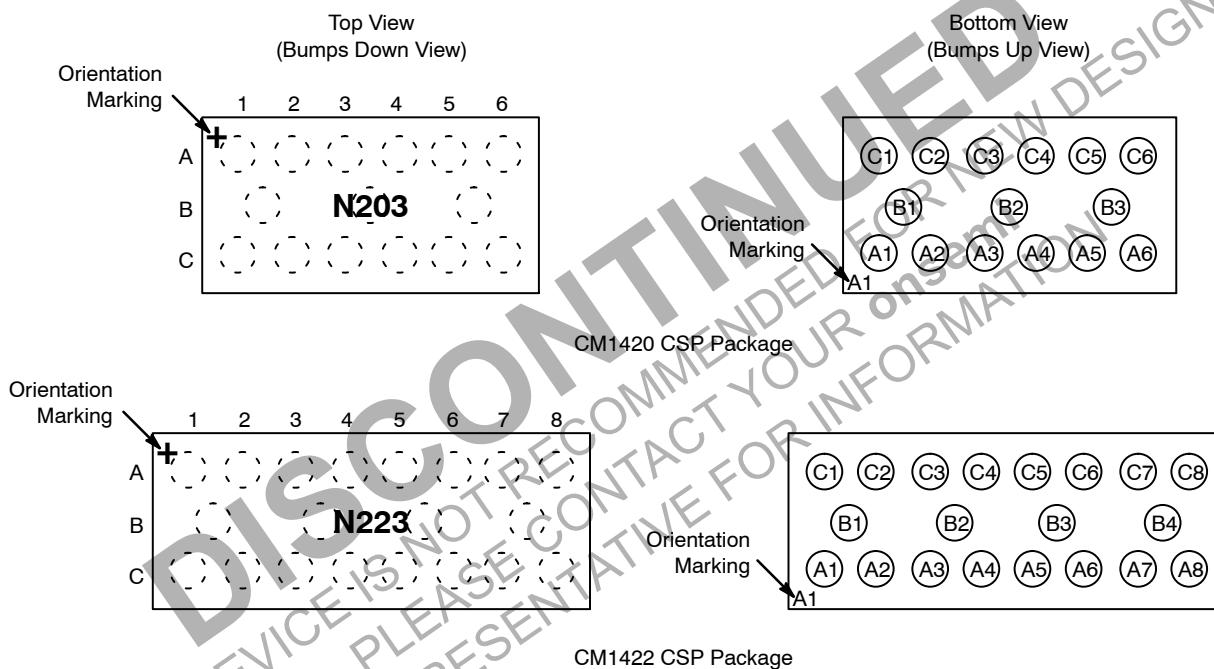


Table 1. PIN DESCRIPTIONS

CM1420	CM1422	Name	Description	CM1420	CM1422	Name	Description
Pin(s)	Pin(s)			Pin(s)	Pin(s)		
A1	A1	FILTER1	Filter Channel 1	C1	C1	FILTER1	Filter Channel 1
A2	A2	FILTER2	Filter Channel 2	C2	C2	FILTER2	Filter Channel 2
A3	A3	FILTER3	Filter Channel 3	C3	C3	FILTER3	Filter Channel 3
A4	A4	FILTER4	Filter Channel 4	C4	C4	FILTER4	Filter Channel 4
A5	A5	FILTER5	Filter Channel 5	C5	C5	FILTER5	Filter Channel 5
A6	A6	FILTER6	Filter Channel 6	C6	C6	FILTER6	Filter Channel 6
-	A7	FILTER7	Filter Channel 7	-	C7	FILTER7	Filter Channel 7
-	A8	FILTER8	Filter Channel 8	-	C8	FILTER8	Filter Channel 8
B1-B3	B1-B4	GND	Device Ground				

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Unit
Storage Temperature Range	-65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	500	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Unit
Operating Temperature Range	-40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R	Resistance		80	100	120	Ω
C	Capacitance	At 2.5 V DC, 1 MHz, 30 mV AC	12	15	18	pF
V _{DIODE}	Diode Standoff Voltage	I _{DIODE} = 10 μ A		6.0		V
I _{LEAK}	Diode Leakage Current (reverse bias)	V _{DIODE} = 3.3 V		100	200	nA
V _{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	I _{LOAD} = 10 mA (Note 3)	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	(Note 2)	± 30 ± 15			kV
R _{DYN}	Dynamic Resistance Positive Negative			2.30 0.90		Ω
f _C	Cut-off Frequency Z _{SOURCE} = 50 Ω , Z _{LOAD} = 50 Ω	R = 100 Ω , C = 15 pF		120		MHz

1. T_A = 25°C unless otherwise specified.
2. ESD applied to input and output pins with respect to GND, one at a time.
3. Clamping voltage is measured at the opposite side of the EMI filter to the ESD pin. For example, if ESD is applied to Pin A1, then clamping voltage is measured at Pin C1.

PERFORMANCE INFORMATION

Typical Filter Performance ($T_A = 25^\circ\text{C}$, DC Bias = 0 V, 50 Ω Environment)

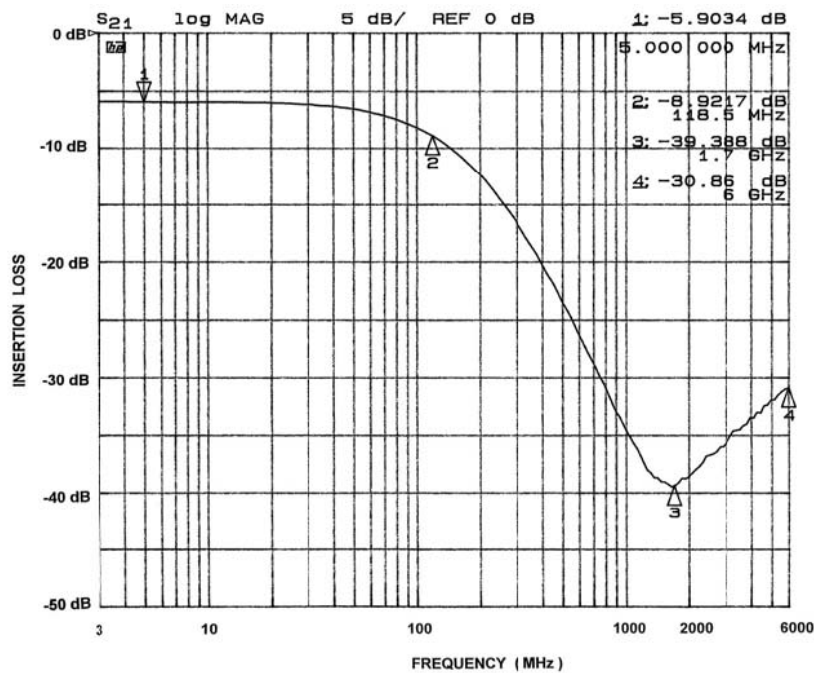


Figure 1. Insertion Loss vs. Frequency (A1-C1 to GND B1)

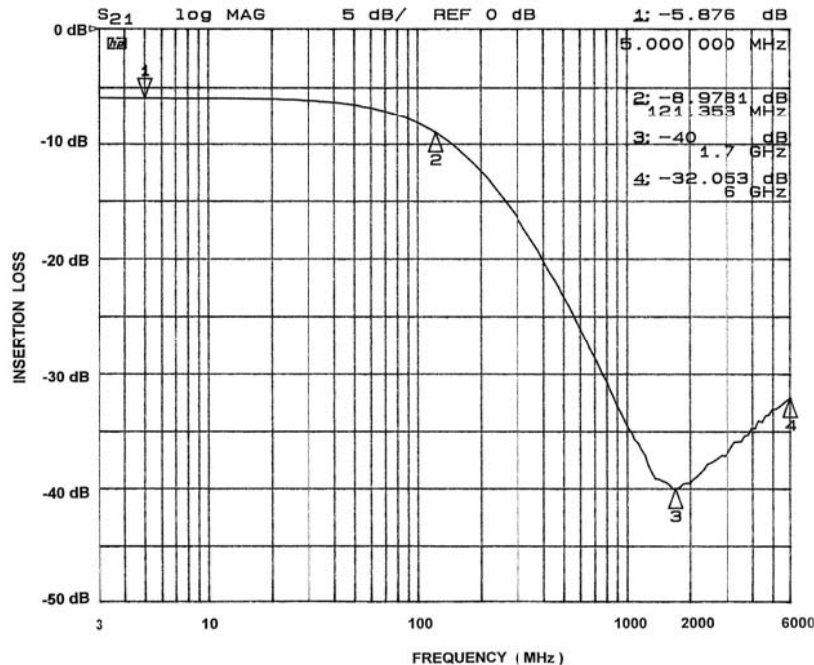


Figure 2. Insertion Loss vs. Frequency (A2-C2 to GND B1)

PERFORMANCE INFORMATION (continued)

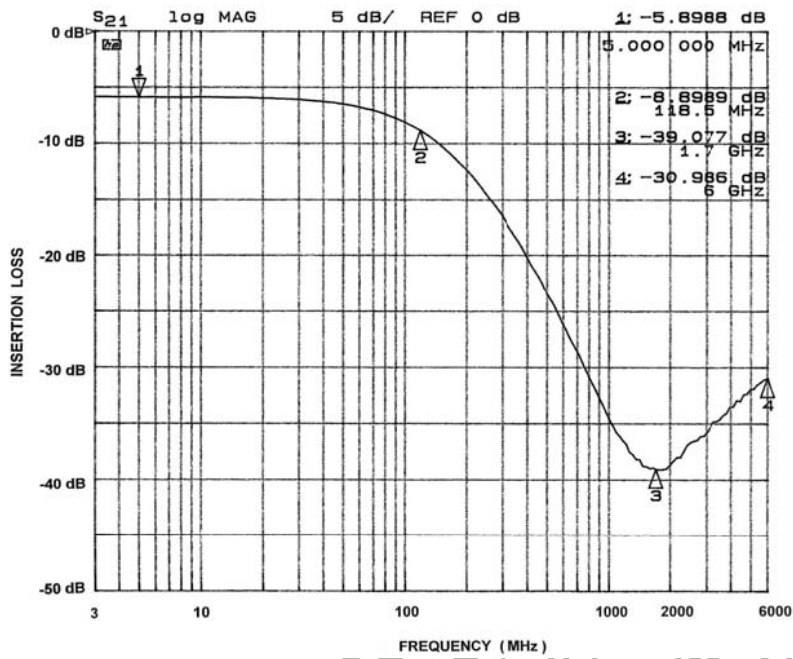
Typical Filter Performance ($T_A = 25^\circ\text{C}$, DC Bias = 0 V, 50 Ω Environment)

Figure 3. Insertion Loss vs. Frequency (A3-C3 to GND B2)

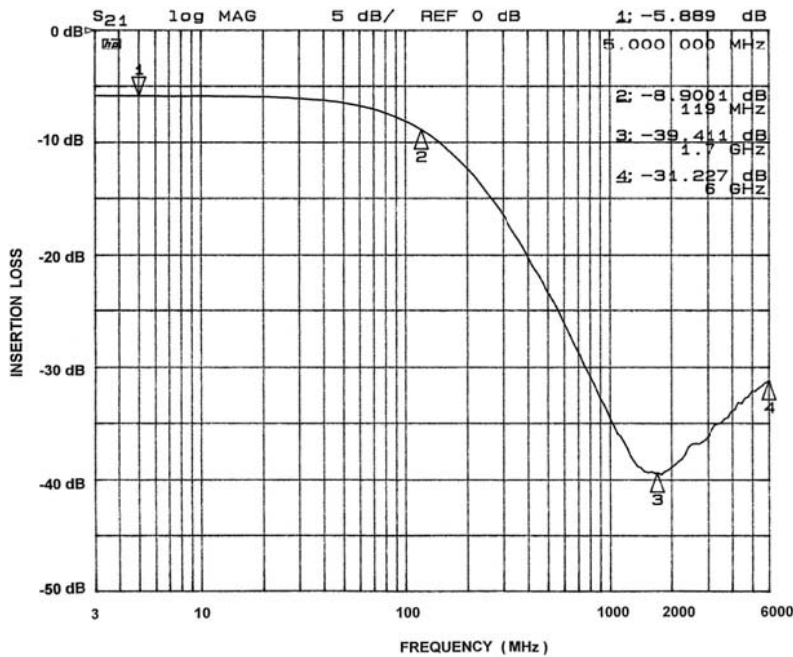


Figure 4. Insertion Loss vs. Frequency (A4-C4 to GND B2)

PERFORMANCE INFORMATION (continued)

Typical Filter Performance ($T_A = 25^\circ\text{C}$, DC Bias = 0 V, 50 Ω Environment)

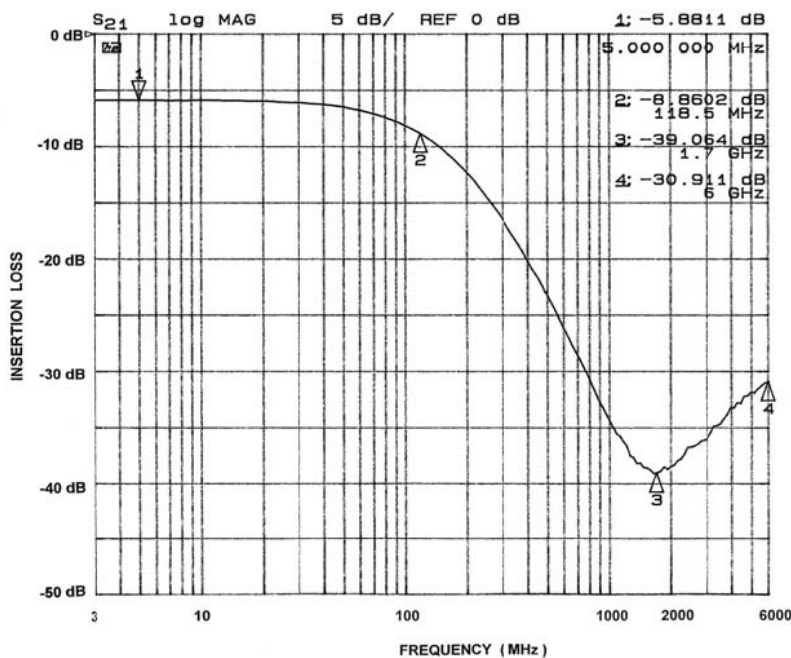


Figure 5. Insertion Loss vs. Frequency (A5-C5 to GND B3)

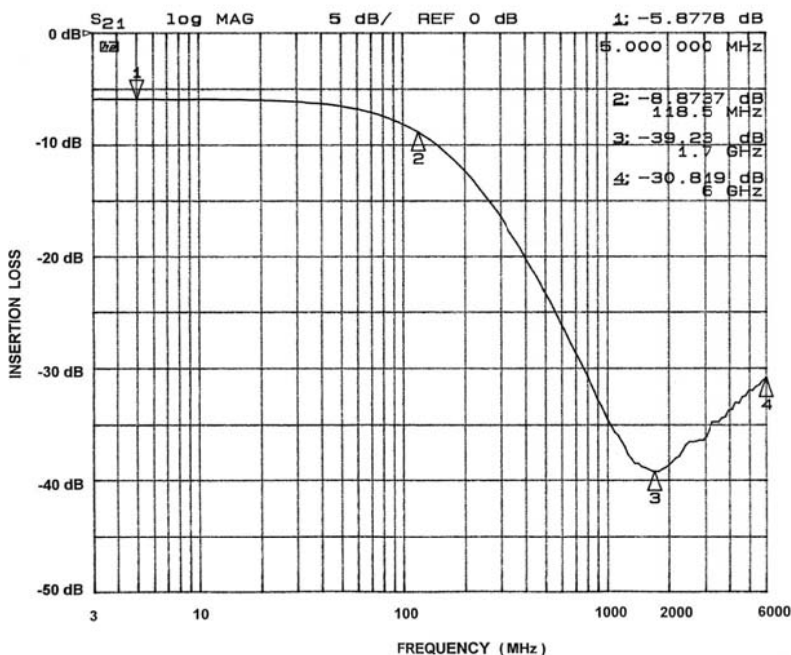
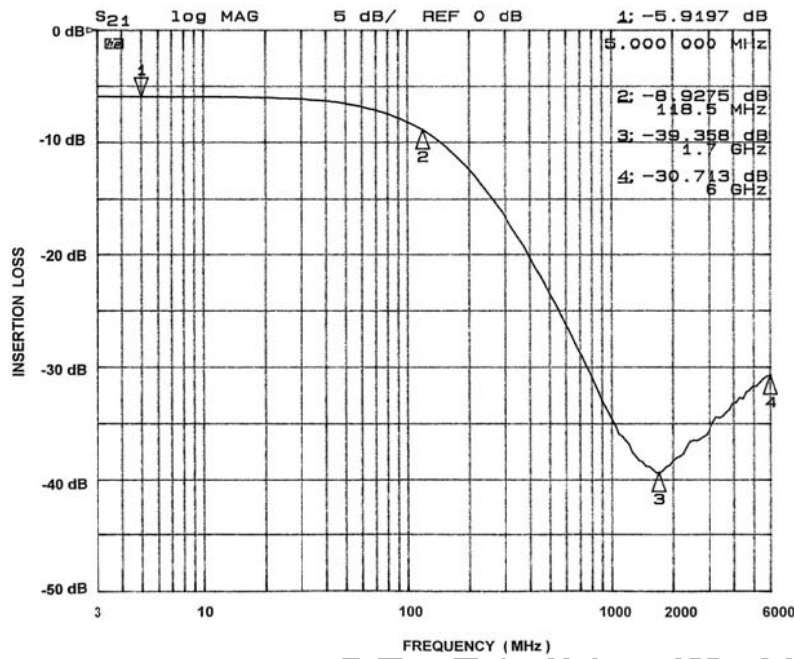
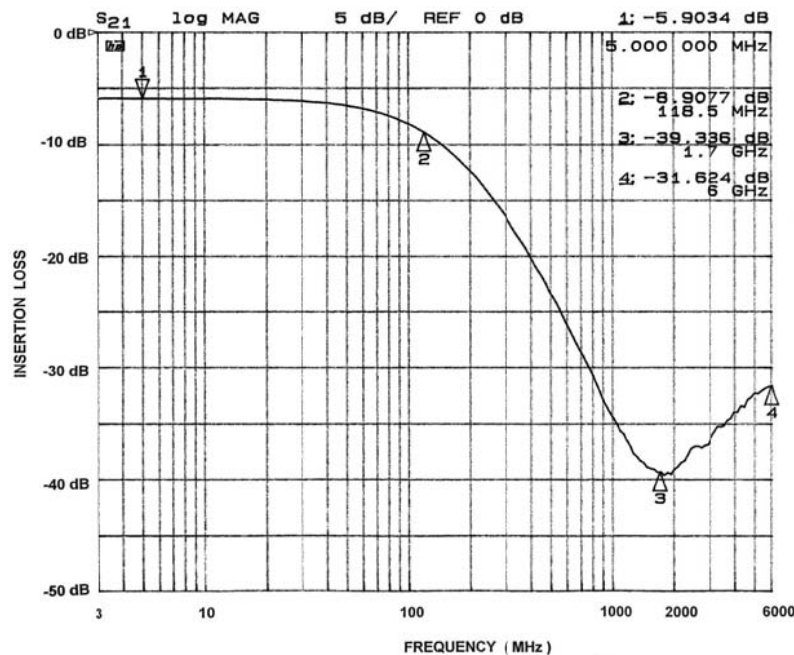


Figure 6. Insertion Loss vs. Frequency (A6-C6 to GND B3)

PERFORMANCE INFORMATION (continued)

Typical Filter Performance ($T_A = 25^\circ\text{C}$, DC Bias = 0 V, 50 Ω Environment)Figure 7. Insertion Loss vs. Frequency
(A7-C7 to GND B4, CM1422 Only)Figure 8. Insertion Loss vs. Frequency
(A8-C8 to GND B4, CM1422 Only)

PERFORMANCE INFORMATION (continued)

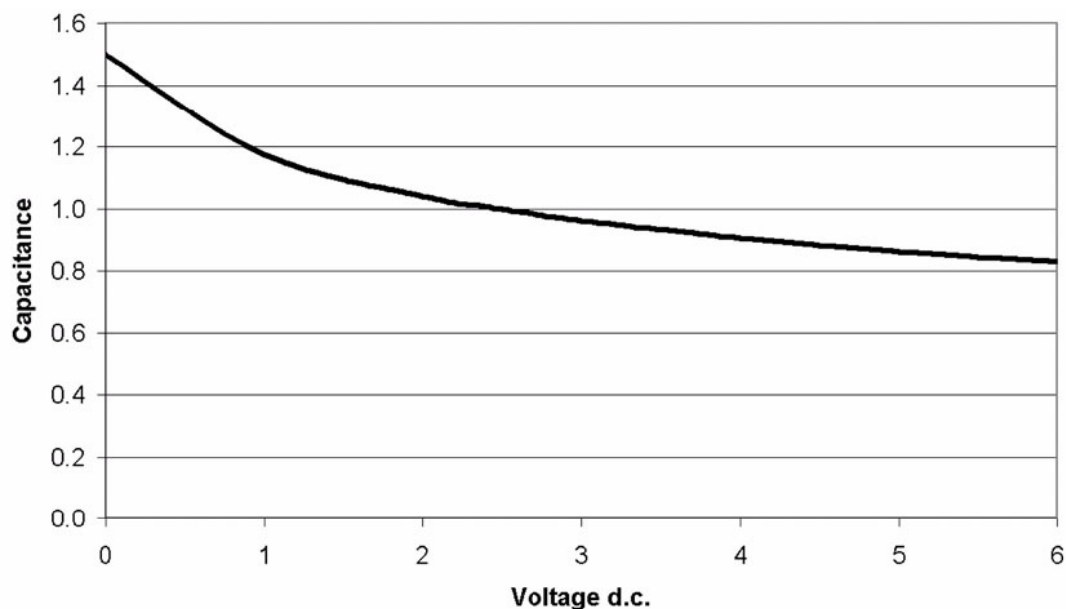


Figure 9. Filter Capacitance vs. Input Voltage over Temperature
(normalized to capacitance at 2.5 VDC and 25°C)

DISCONTINUED
THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGNS
PLEASE CONTACT YOUR onsemi REPRESENTATIVE FOR INFORMATION

APPLICATION INFORMATION

Table 5. PRINTED CIRCUIT BOARD RECOMMENDATIONS

Parameter	Value
Pad Size on PCB	0.240 mm
Pad Shape	Round
Pad Definition	Non-Solder Mask defined pads
Solder Mask Opening	0.290 mm Round
Solder Stencil Thickness	0.125 – 0.150 mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.300 mm Round
Solder Flux Ratio	50/50 by volume
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance – Edge To Corner Ball	±50 μ m
Solder Ball Side Coplanarity	±20 μ m
Maximum Dwell Time Above Liquidous	60 seconds
Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste	260°C

Non-Solder Mask Defined Pad
0.240 mm DIA.

Solder Stencil Opening
0.300 mm DIA.

Solder Mask Opening
0.290 mm DIA.

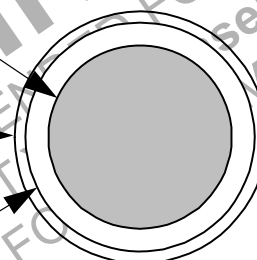


Figure 10. Recommended Non-Solder Mask Defined Pad Illustration

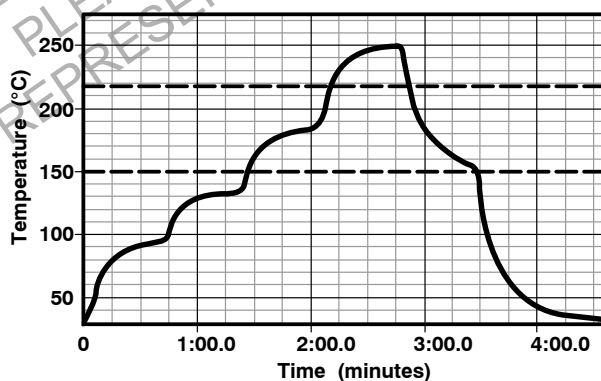


Figure 11. Lead-free (SnAgCu) Solder Ball Reflow Profile

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

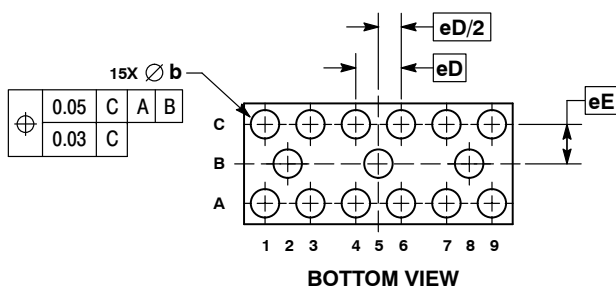
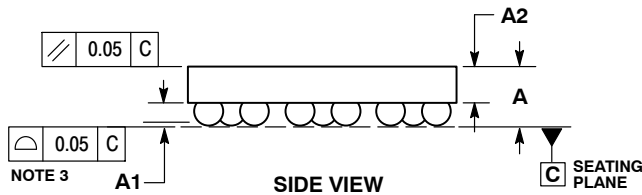
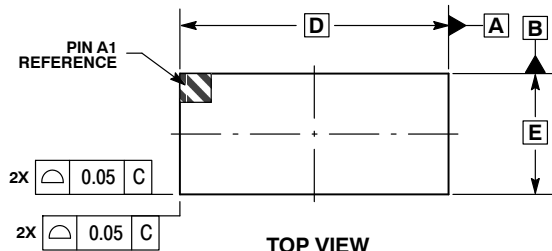
ON Semiconductor®



SCALE 4:1

WLCSP15, 2.96x1.33
CASE 567BS-01
ISSUE O

DATE 26 JUL 2010

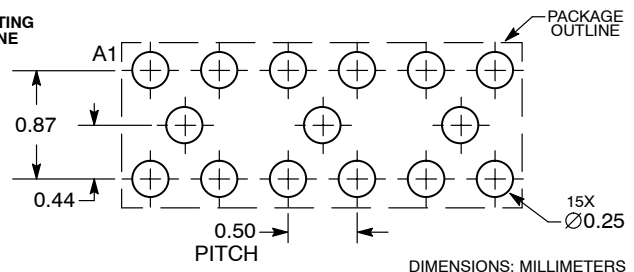


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40	REF
b	0.29	0.35
D	2.96	BSC
E	1.33	BSC
eD	0.50	BSC
eE	0.435	BSC

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER: 98AON49826E

Electronic versions are uncontrolled except when accessed directly from the Document Repository.
Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION: WLCSP15, 2.96X1.33

PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

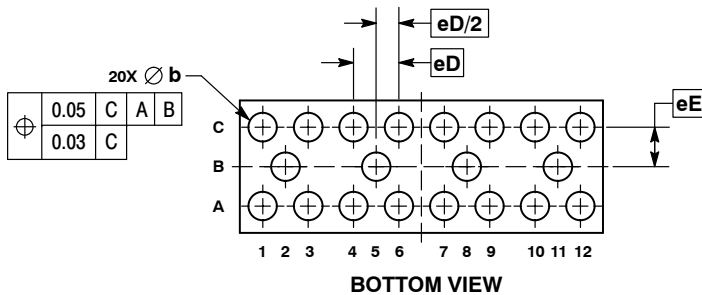
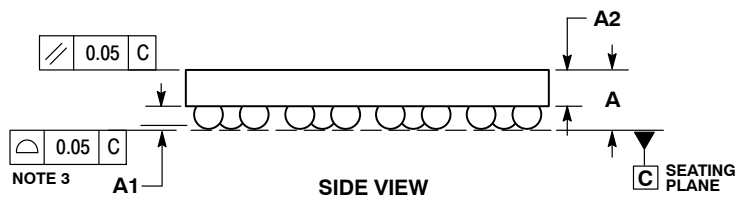
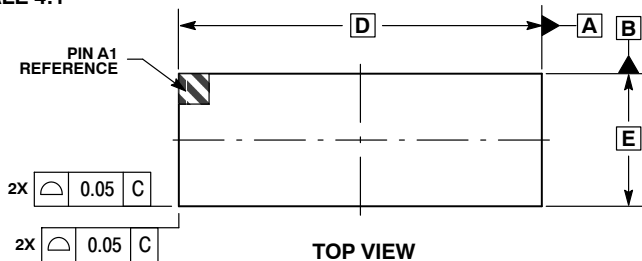
ON Semiconductor®



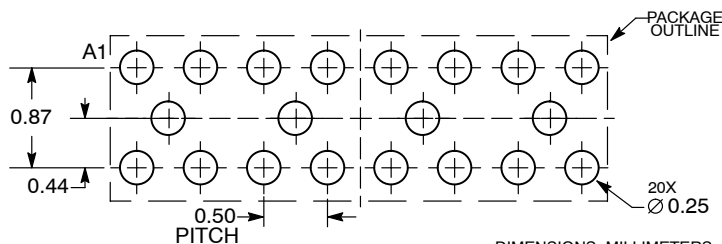
SCALE 4:1

WLCSP20, 4.00x1.46
CASE 567BZ-01
ISSUE O

DATE 26 JUL 2010



RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40	REF
b	0.29	0.35
D	4.00	BSC
E	1.46	BSC
eD	0.50	BSC
eE	0.435	BSC

DOCUMENT NUMBER: 98AON49833E

Electronic versions are uncontrolled except when accessed directly from the Document Repository.
Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION: WLCSP20, 4.00X1.46

PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales